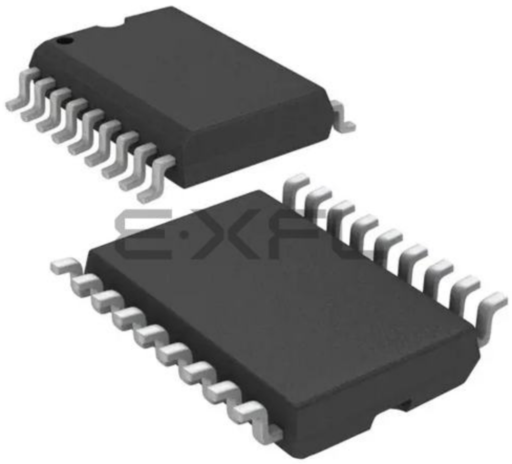

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c54c-04e-so

2.0 PIC16C5X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC16C5X Product Identification System at the back of this data sheet to specify the correct part number.

For the PIC16C5X family of devices, there are four device types, as indicated in the device number:

1. **C**, as in PIC16**C**54C. These devices have EPROM program memory and operate over the standard voltage range.
2. **LC**, as in PIC16**LC**54A. These devices have EPROM program memory and operate over an extended voltage range.
3. **CR**, as in PIC16**CR**54A. These devices have ROM program memory and operate over the standard voltage range.
4. **LCR**, as in PIC16**LCR**54A. These devices have ROM program memory and operate over an extended voltage range.

2.1 UV Erasable Devices (EPROM)

The UV erasable versions offered in CERDIP packages, are optimal for prototype development and pilot programs.

UV erasable devices can be programmed for any of the four oscillator configurations. Microchip's PICSTART® Plus**(1)** and PRO MATE® programmers both support programming of the PIC16C5X. Third party programmers also are available. Refer to the Third Party Guide (DS00104) for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates, or small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must be programmed.

Note 1: PIC16LC54C and PIC16C54A devices require OSC2 not to be connected while programming with PICSTART® Plus programmer.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production (SQTP℠) Devices

Microchip offers the unique programming service where a few user defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory.

Serial programming allows each device to have a unique number which can serve as an entry code, password or ID number.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, giving the customer a low cost option for high volume, mature products.

TABLE 3-1: PINOUT DESCRIPTION - PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58, PIC16CR58

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0 RA1 RA2 RA3	17 18 1 2	17 18 1 2	19 20 1 2	I/O I/O I/O I/O	TTL TTL TTL TTL	Bi-directional I/O port
RB0 RB1 RB2 RB3 RB4 RB5 RB6 RB7	6 7 8 9 10 11 12 13	6 7 8 9 10 11 12 13	7 8 9 10 11 12 13 14	I/O I/O I/O I/O I/O I/O I/O I/O	TTL TTL TTL TTL TTL TTL TTL TTL	Bi-directional I/O port
T0CKI	3	3	3	I	ST	Clock input to Timer0. Must be tied to V_{SS} or V_{DD}, if not in use, to reduce current consumption.
$\overline{MCLR}/V_{PP}$	4	4	4	I	ST	Master clear (RESET) input/programming voltage input. This pin is an active low RESET to the device. Voltage on the $\overline{MCLR}/V_{PP}$ pin must not exceed V_{DD} to avoid unintended entering of Programming mode.
OSC1/CLKIN	16	16	18	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
V_{DD}	14	14	15,16	P	—	Positive supply for logic and I/O pins.
V_{SS}	5	5	5,6	P	—	Ground reference for logic and I/O pins.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

PIC16C5Xs can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

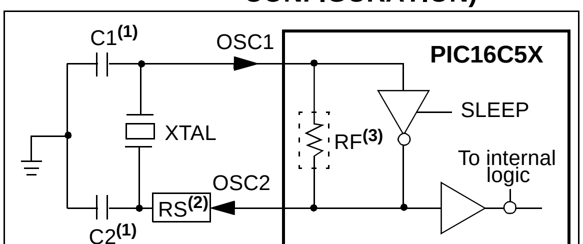
1. LP: Low Power Crystal
2. XT: Crystal/Resonator
3. HS: High Speed Crystal/Resonator
4. RC: Resistor/Capacitor

Note:	Not all oscillator selections available for all parts. See Section 9.1.

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16C5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the Oscillator mode chosen (approx. value = 10 MΩ).

FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

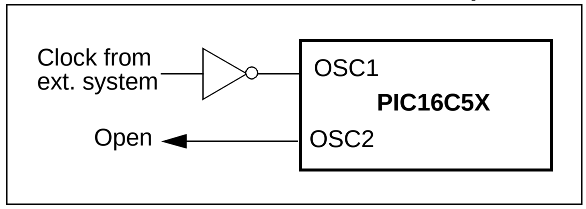


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS - PIC16C5X, PIC16CR5X

Osc Type	Resonator Freq	Cap. Range C1	Cap. Range C2
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-33 pF 10-22 pF	68-100 pF 15-33 pF 10-22 pF
HS	8.0 MHz 16.0 MHz	10-22 pF 10 pF	10-22 pF 10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR - PIC16C5X, PIC16CR5X

Osc Type	Crystal Freq	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz 200 kHz 455 kHz 1 MHz 2 MHz 4 MHz	15-30 pF 15-30 pF 15-30 pF 15-30 pF 15 pF 15 pF	200-300 pF 100-200 pF 15-100 pF 15-30 pF 15 pF 15 pF
HS	4 MHz 8 MHz 20 MHz	15 pF 15 pF 15 pF	15 pF 15 pF 15 pF

Note 1: For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note:	If you change from this device to another device, please verify oscillator characteristics in your application.

4.4 RC Oscillator

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 4-5 shows how the R/C combination is connected to the PIC16C5X. For REXT values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high REXT values (e.g., 1 MΩ) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping REXT between 3 kΩ and 100 kΩ.

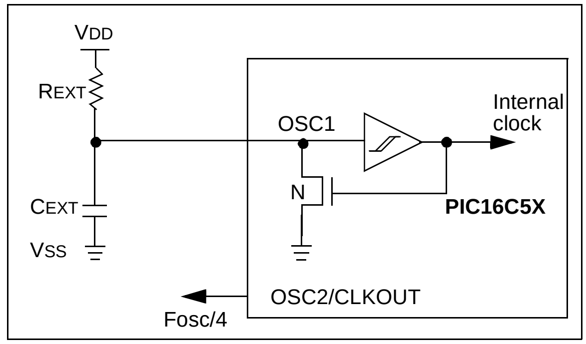
Although the oscillator will operate with no external capacitor (CEXT = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to VDD for given REXT/CEXT values as well as frequency variation due to operating temperature for given R, C, and VDD values.

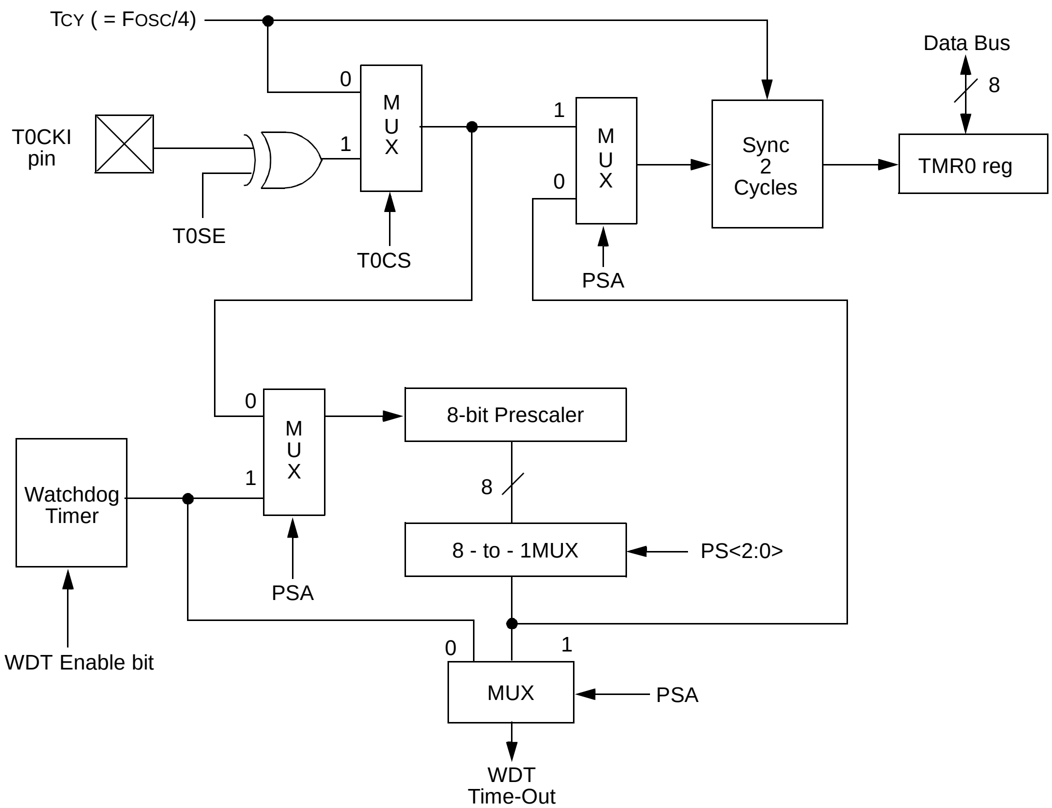
The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic.

FIGURE 4-5: RC OSCILLATOR MODE



Note: If you change from this device to another device, please verify oscillator characteristics in your application.

FIGURE 8-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS<2:0> are bits in the OPTION register.

12.2 DC Characteristics: PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage** PIC16C5X-RCI PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-LPI	 3.0 3.0 4.5 4.5 2.5	 — — — — —	 6.25 6.25 5.5 5.5 6.25	 V V V V V	
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current**(2) PIC16C5X-RCI(3) PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI PIC16C5X-LPI	 — — — — — —	 1.8 1.8 4.8 4.8 9.0 15	 3.3 3.3 10 10 20 40	 mA mA mA mA mA μA	 FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 20 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	IPD	**Power-down Current**(2)	— —	4.0 0.6	14 12	μA μA	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in “Typ” column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

12.5 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	V_{IL}	**Input Low Voltage**					
		I/O ports	Vss	—	0.15 VDD	V	Pin at hi-impedance
		$\overline{MCLR}$ (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	Vss	—	0.15 VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	Vss	—	0.3 VDD	V	PIC16C5X-XT, 10, HS, LP
D040	V_{IH}	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5 V
		$\overline{MCLR}$ (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	0.7 VDD	—	VDD	V	PIC16C5X-XT, 10, HS, LP
D050	V_{HYS}	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	I_{IL}	**Input Leakage Current (1,2)**					**For VDD ≤ 5.5 V:**
		I/O ports	–1	0.5	+1	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5	—	—	μA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5	μA	VPIN = VDD
		T0CKI	–3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD
		OSC1	–3	0.5	+3	μA	VSS ≤ VPIN ≤ VDD, PIC16C5X-XT, 10, HS, LP
D080	V_{OL}	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	V_{OH}	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{MCLR}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

13.0 ELECTRICAL CHARACTERISTICS - PIC16CR54A

Absolute Maximum Ratings(†)

Ambient Temperature under bias	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}	0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS}[(1)]	0 to +14V
Voltage on all other pins with respect to V_{SS}	–0.6V to (V_{DD} + 0.6V)
Total power dissipation[(2)]	800 mW
Max. current out of V_{SS} pin	150 mA
Max. current into V_{DD} pin	50 mA
Max. current into an input pin (T0CKI only)	±500 μA
Input clamp current, I_{IK} (VI < 0 or VI > V_{DD})	±20 mA
Output clamp current, I_{OK} (V0 < 0 or V0 > V_{DD})	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O port (PORTA or B)	40 mA
Max. output current sunk by a single I/O port (PORTA or B)	50 mA

Note 1: Voltage spikes below Vss at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA may cause latch-up. Thus, a series resistor of 50 to 100 Ω should be used when applying a low level to the $\overline{MCLR}$ pin rather than pulling this pin directly to Vss.

2: Power Dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 14-2: TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 20 PF

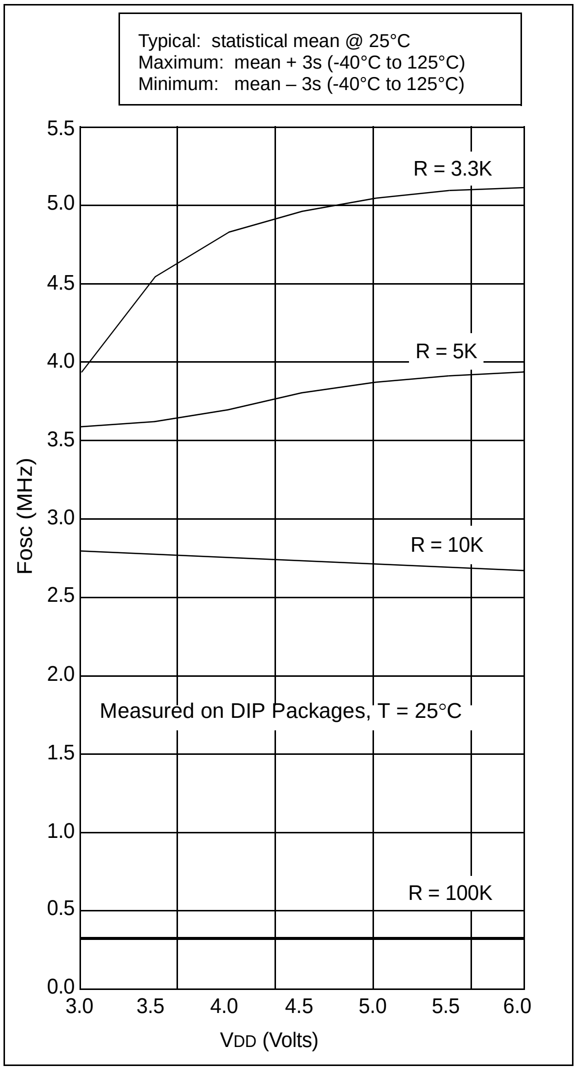
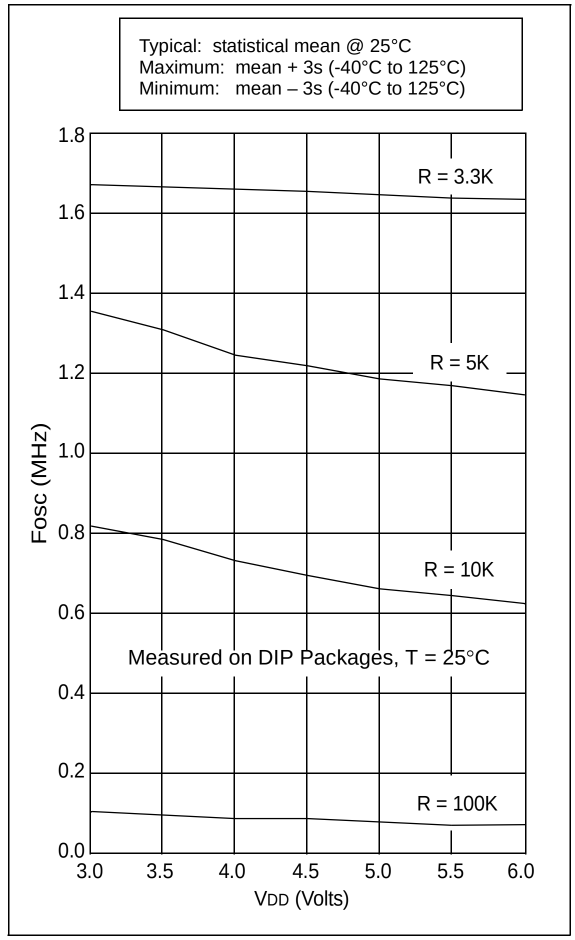


FIGURE 14-3: TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 100 PF



15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
PIC16C54A-04E, 10E, 20E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IPD	**Power-down Current(2)**					
D020		PIC16LC54A	—	2.5	15	μA	VDD = 2.5V, WDT enabled, Extended
			—	0.25	7.0	μA	VDD = 2.5V, WDT disabled, Extended
D020A		PIC16C54A	—	5.0	22	μA	VDD = 3.5V, WDT enabled
			—	0.8	18*	μA	VDD = 3.5V, WDT disabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

15.4 DC Characteristics: PIC16C54A-04, 10, 20, PIC16LC54A-04, PIC16LV54A-02 (Commercial) PIC16C54A-04I, 10I, 20I, PIC16LC54A-04I, PIC16LV54A-02I (Industrial) PIC16C54A-04E, 10E, 20E, PIC16LC54A-04E (Extended)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial-PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	RC mode only(3)
		OSC1	VSS	—	0.3 VDD		XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	0.2 VDD + 1	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	-1.0	0.5	+1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		$\overline{\text{MCLR}}$	-5.0	—	+5.0	μA	VPIN = VSS +0.25V
		$\overline{\text{MCLR}}$	—	0.5	+3.0	μA	VPIN = VDD
		T0CKI	-3.0	0.5	+3.0	μA	VSS ≤ VPIN ≤ VDD
		OSC1	-3.0	0.5	—	μA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
	VOH	**Output High Voltage(2)**					
		I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD - 0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

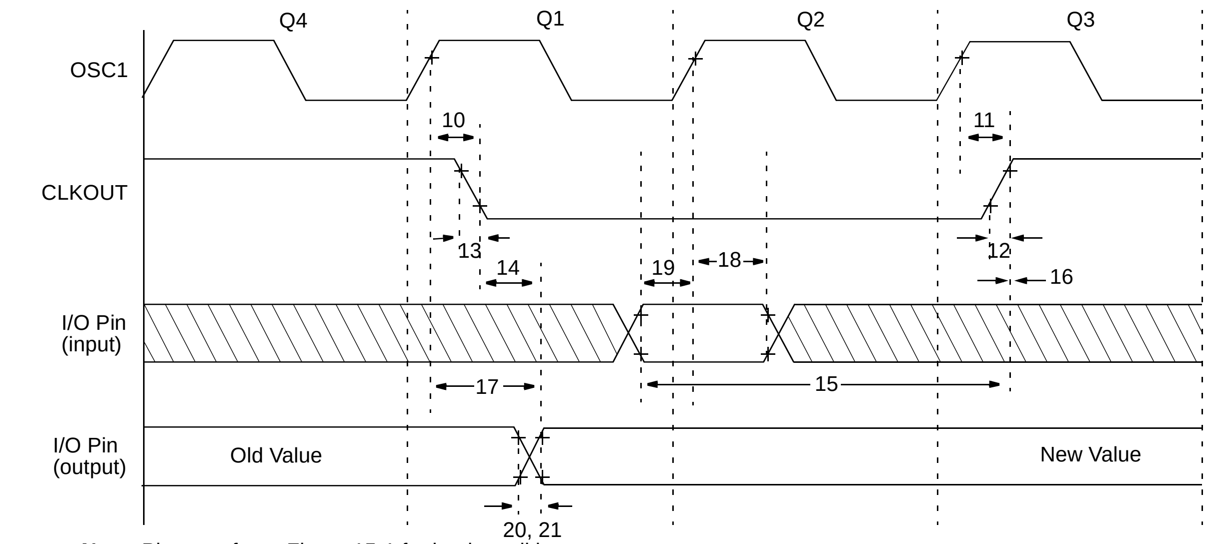
† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

FIGURE 15-3: CLKOUT AND I/O TIMING - PIC16C54A



Note: Please refer to Figure 15-1 for load conditions.

TABLE 15-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54A

AC Characteristics	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**
10	TosH2ckL	OSC1↑ to CLKOUT↓(1)	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑(1)	—	15	30**	ns
12	TckR	CLKOUT rise time(1)	—	5.0	15**	ns
13	TckF	CLKOUT fall time(1)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑(1)	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑(1)	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid(2)	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time(2)	—	10	25**	ns
21	TioF	Port output fall time(2)	—	10	25**	ns

* These parameters are characterized but not tested.
** These parameters are design targets and are not tested. No characterization data available at this time.
† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.
2: Please refer to Figure 15-1 for load conditions.

FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 20 pF, 25°C

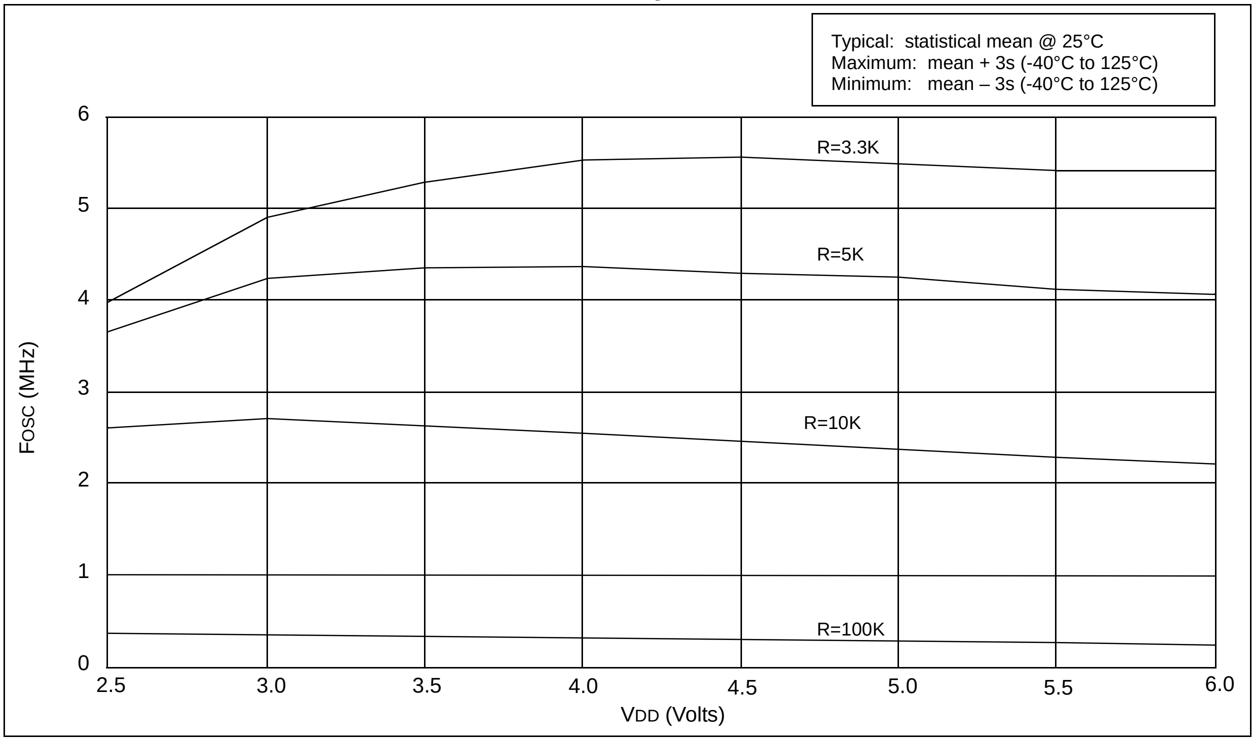


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 100 pF, 25°C

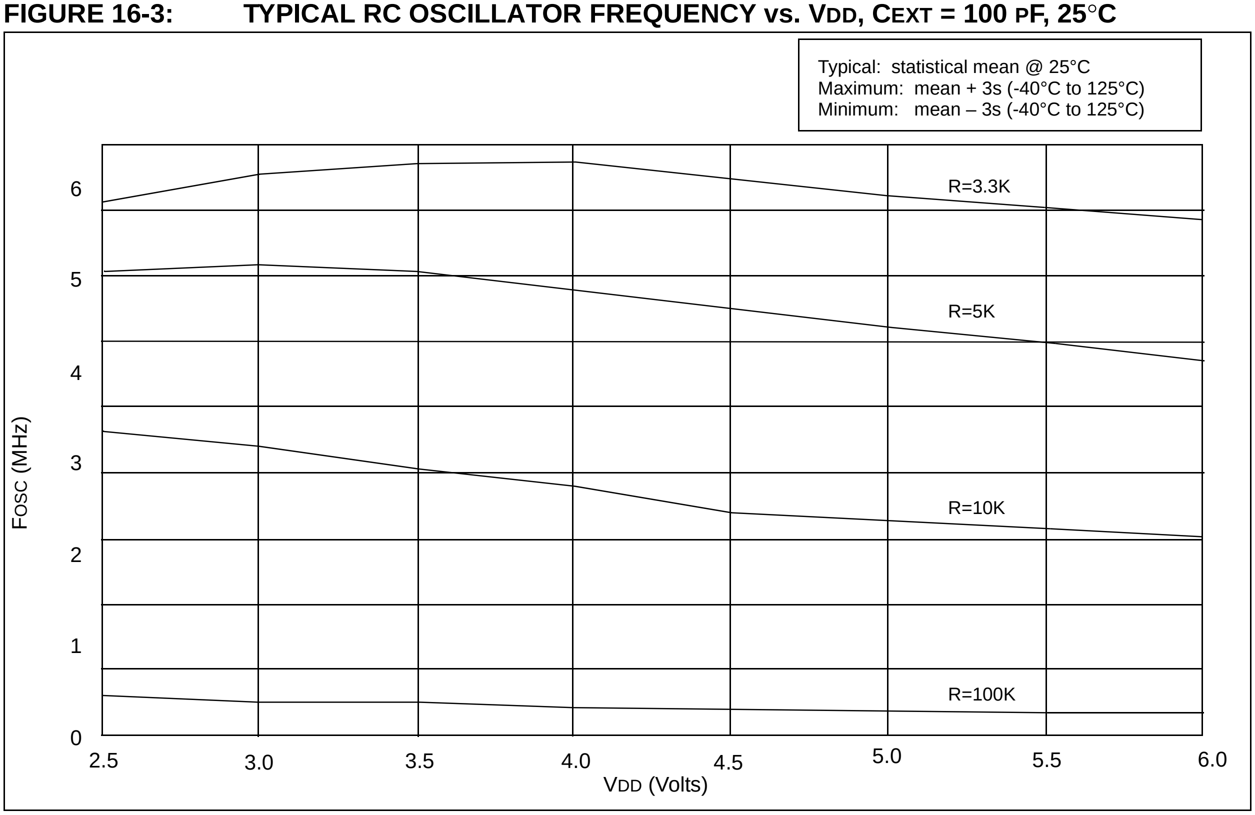
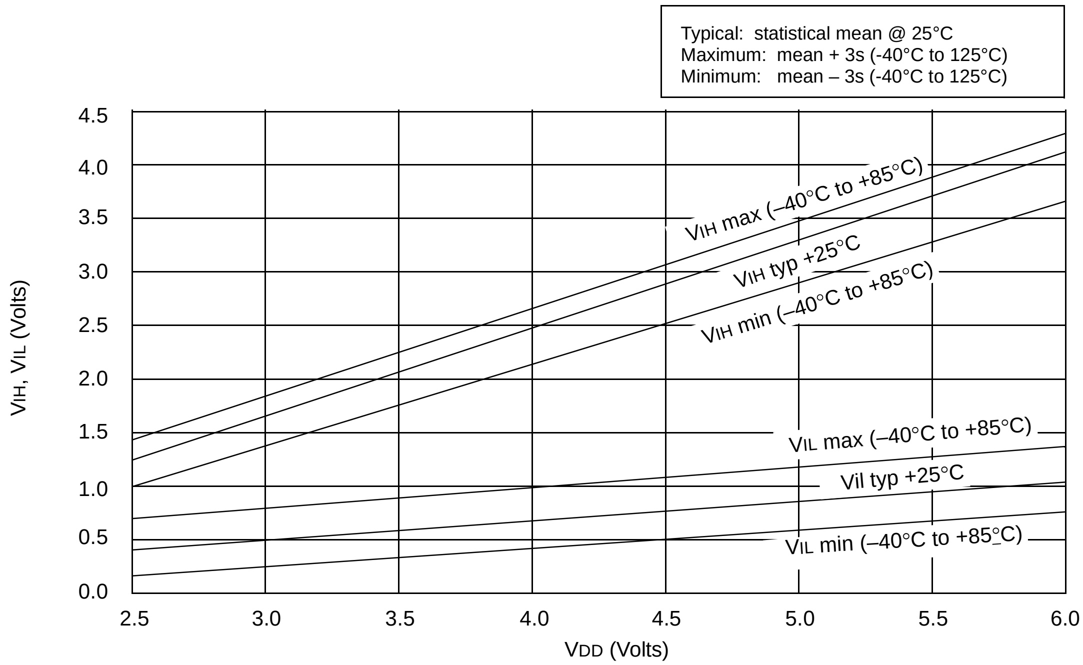


FIGURE 16-9: VIH, VIL OF MCLR, T0CKI AND OSC1 (IN RC MODE) vs. VDD



Note: These input pins have Schmitt Trigger input buffers.

 Preliminary

FIGURE 16-10: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)

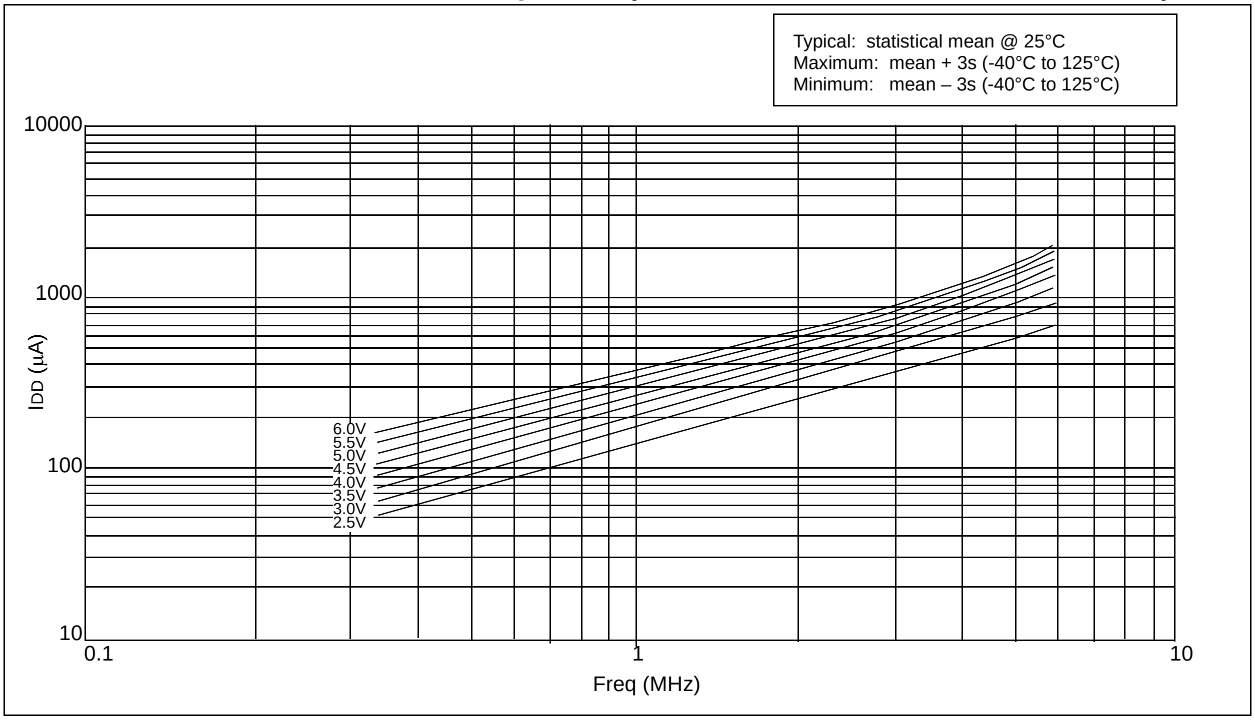


FIGURE 16-11: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, –40°C to +85°C)

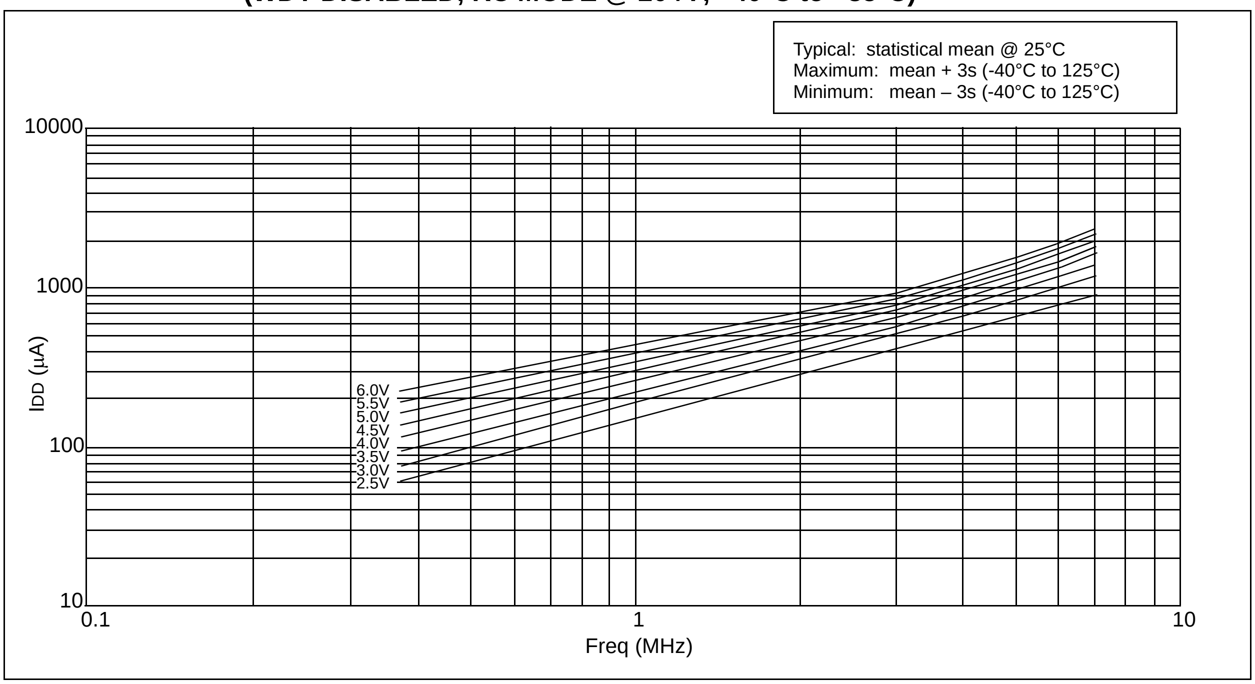
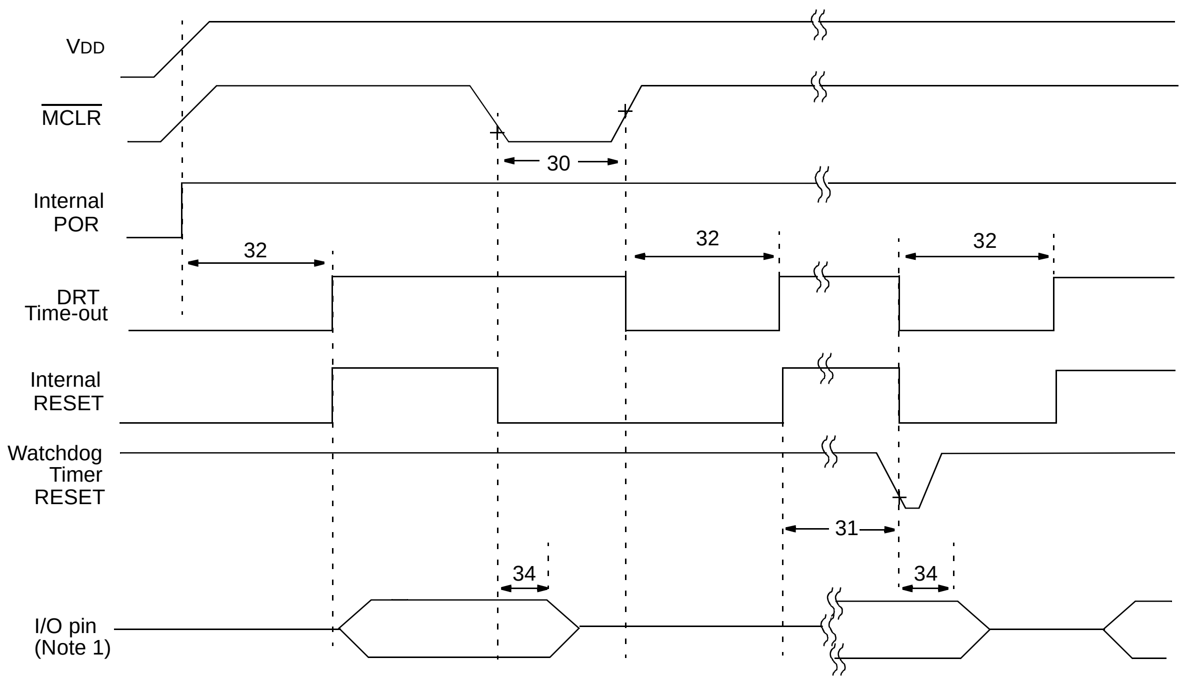


FIGURE 17-8: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X, PIC16CR5X



Note 1: Please refer to Figure 17-5 for load conditions.

TABLE 17-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X, PIC16CR5X

AC Characteristics	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	1000*	—	—	ns	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low	100*	300*	1000*	ns	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 300 pF, 25°C

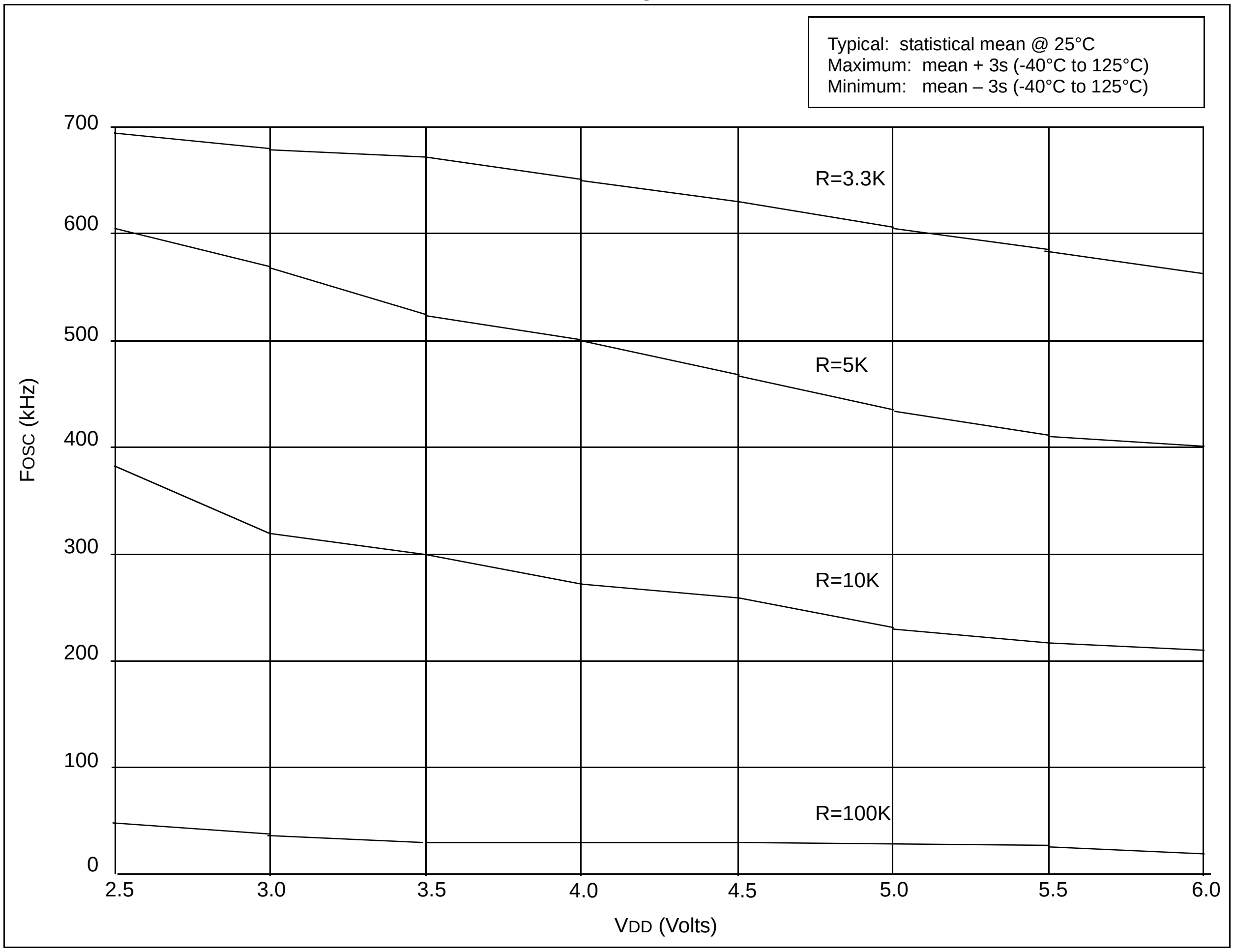


FIGURE 18-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)

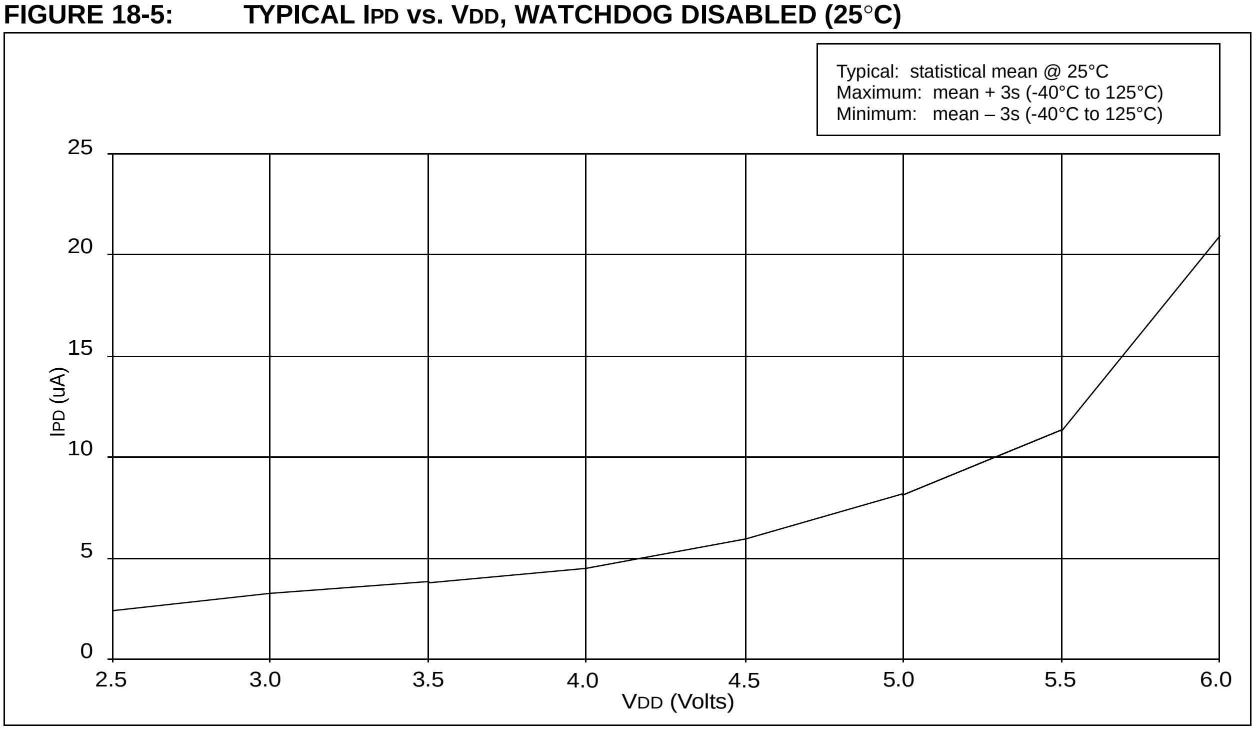


FIGURE 18-12: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, 25°C)

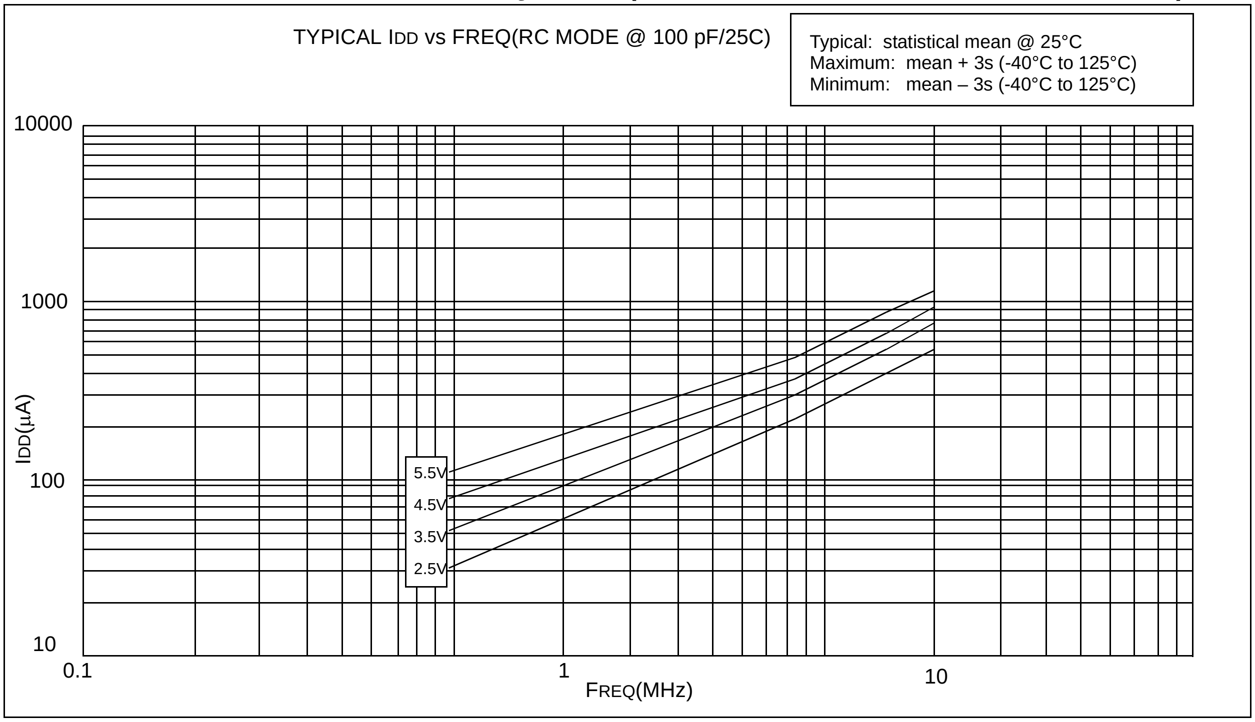


FIGURE 18-13: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)

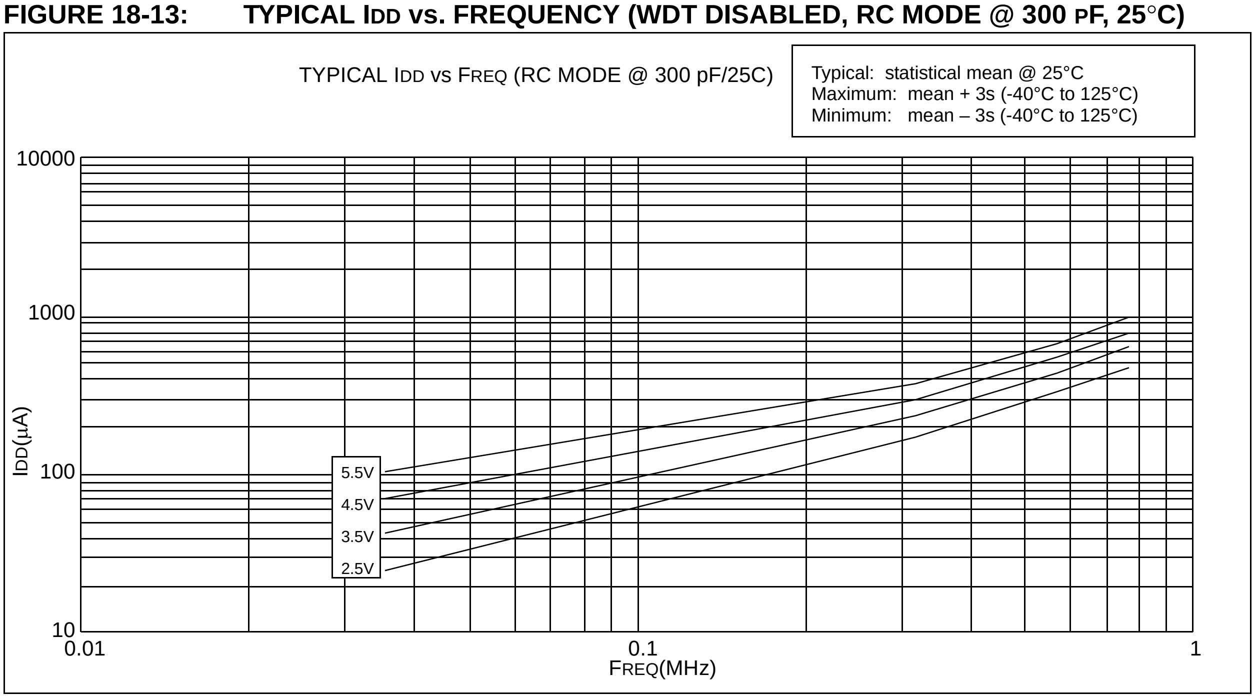
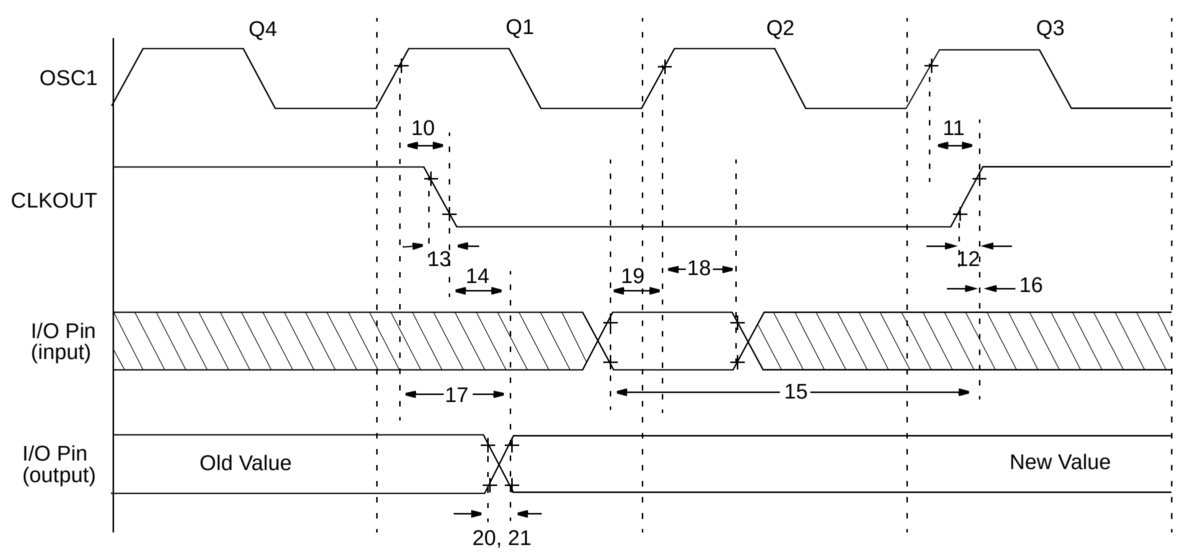


FIGURE 19-4: CLKOUT AND I/O TIMING - PIC16C5X-40



Note: Refer to Figure 19-2 for load conditions.

TABLE 19-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X-40

AC Characteristics		**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**
10	TosH2ckL	OSC1↑ to CLKOUT↓(1,2)	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑(1,2)	—	15	30**	ns
12	TckR	CLKOUT rise time(1,2)	—	5.0	15**	ns
13	TckF	CLKOUT fall time(1,2)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid(1,2)	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑(1,2)	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑(1,2)	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid(2)	—	—	100	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time(2)	—	10	25**	ns
21	TioF	Port output fall time(2)	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Refer to Figure 19-2 for load conditions.